

Announcement and Call for Abstracts Topical Workshop on **Automotive Semiconductor Packaging**

This workshop is being held as a part of the 15th International Device Packaging Conference

**WeKoPa Resort & Casino
Fountain Hills, Arizona - USA
March 4 - 7, 2019**

Technical Chair:	Technical Co-Chair:
Prasad Dhond, Amkor Technology prasad.dhond@amkor.com	Tu-Anh Tran, NXP tu-anh.tran@nxp.com

Automotive Organizing Committee:

Charles Lee, ASE, charles.lee@aseus.com
Mark Gerber, ASE, mark.gerber@aseus.com

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Automotive Workshop Focus:

Automotive is one of the fastest growing applications in the semiconductor industry. Semiconductor packaging plays a critical role in achieving Zero Defects and High Reliability in the car. This automotive track is focused on bringing together experts to discuss the automotive landscape, packaging requirements and how the industry is addressing challenges. Although a majority of the automotive packaging market is still using wirebond, the use of non-wirebond packages is growing due to Infotainment, ADAS and autonomous driving applications. Presentations and discussions will be focused on material, design, process and controls used in automotive semiconductor packages.

Abstracts are being requested on the following topics:

- Automotive Packaging Market Growth Drivers
- Automotive Quality and Achieving Zero Defects
- High Volume Manufacturing of Automotive Packages
- Design Considerations for Automotive Packaging
- Wafer Level CSP and FanOut in Automotive
- Flipchip Packaging and 2.5D in Automotive
- Solder Joint Reliability for Automotive
- SiPs in Automotive
- Automotive Memory Packaging
- Copper Wires in Automotive Packaging
- ADAS Sensor Packaging (Radar, LiDAR, Image Sensors)
- Managing the Automotive Supply Chain
- Requirements of Automotive Tier 1s and OEMs
- Reliability and Failure Analysis of Advanced Automotive Packages
- Automotive Test and Burn-In

Those wishing to present in the Device Packaging Conference must submit a ~500 word abstract electronically **no later than October 26, 2018**, using the on-line submittal form at: www.imaps.org/abstracts.htm. No formal technical paper is required. A reproduction-ready two- to four-page "extended abstract" with text (figures and graphs included if necessary) will be required for the abstract booklet on January 31, 2019. Please contact Brian Schieman by email at bschieman@imaps.org if you have questions. **STUDENT AUTHORS:** upon abstract submission, please select "yes, I'm a full-time student" on the form and you will automatically be entered in the student competition with \$3000 in foundation awards (\$1500 1st, \$1000 2nd, \$500 3rd).

Device Packaging Exhibit and Technology Show:

IMAPS will hold a concurrent exhibition for vendors and suppliers who support the many aspects of **Automotive Semiconductor Packaging**. This venue features an ideal atmosphere to showcase your products and services to key decision making professionals in the industry. Full 8' by 10' exhibit spaces will be available. To reserve booth space please fill out the on-line submittal form before December 1, 2018 at: www.imaps.org/devicepackaging or contact Brian Schieman by email at bschieman@imaps.org.

Device Packaging Professional Development Courses (PDCs):

For those wishing to broaden their knowledge of device packaging, a selection of half-day courses will be offered on Monday, March 4th, preceding the technical conference. If you would like to participate as an instructor, please submit a description of your short course on-line at www.imaps.org/pdc **no later than October 26, 2018**.